

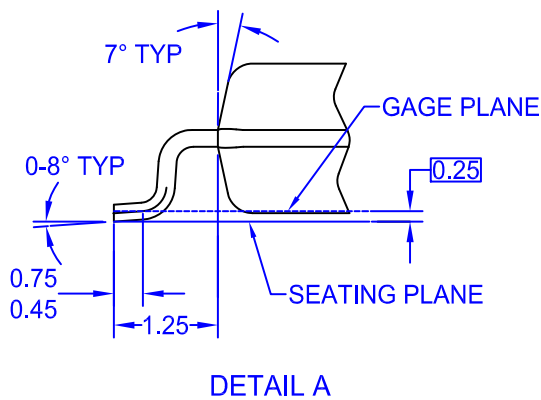
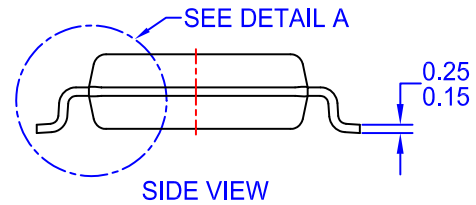
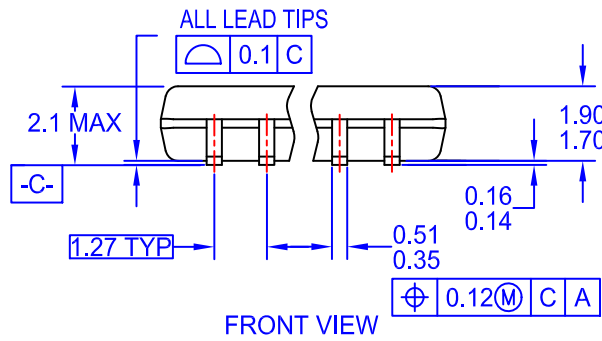
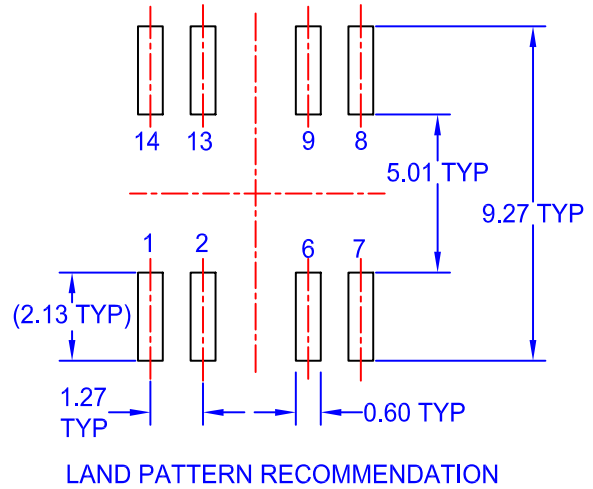
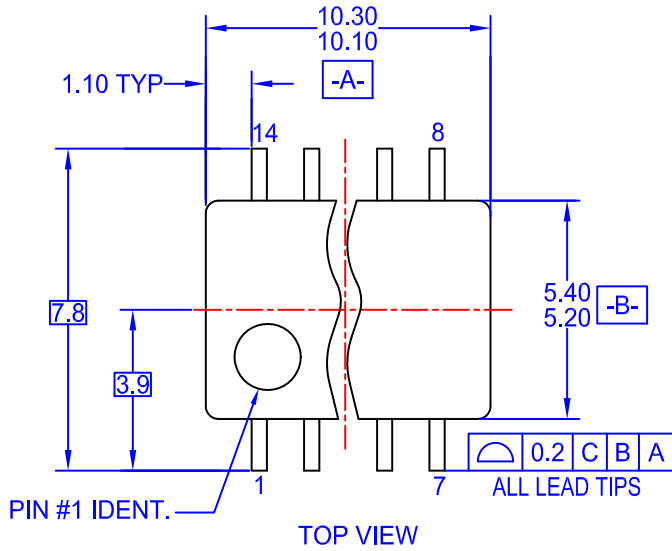
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

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SOP14
CASE 565BE
ISSUE O

DATE 31 DEC 2016



- NOTES:**
- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 - B. DIMENSIONS ARE IN MILLIMETERS.
 - C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

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DESCRIPTION:	SOP14	PAGE 1 OF 1

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